Aillen

1. Part Numbering System:

CLG	<u>05</u>	$\frac{\mathbf{J}}{ }$	$\frac{\mathbf{B}}{ }$	<u>R22</u>
<u>Series Name</u> Chip Resistor: CLG : Thick Film Low Ohm (High power rating and low TCR)	<u>Type</u> Inch (mm) 03-0603(1608) 05-0805(2012) 06-1206(3216) 10-1210(3225) 0A-2010(5025) 12-2512(6432)	$ \frac{\text{Tolerance}}{F= \pm 1\%} $ $ J= \pm 5\% $	Package A=4Kpcs/7"Reel B=5Kpcs/7"Reel C=10Kpcs/7"Reel	$ \frac{\text{Resistance}}{\text{R05=0.05}\Omega} $ R22=0.22 Ω

FEATURE

- 1. High power rating and low TCR
- 2. High reliability and stability
- 3. Reduced size of final equipment
- 4. RoHS exemption free and Lead free products

APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter



DESCRIPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to nominated value within tolerance which controlled by laser trimming of this resistive layer.

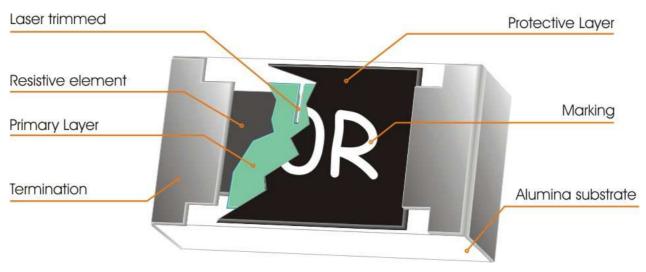
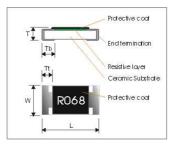


Fig 1. Construction of Chip-R

QUICK REFERENCE DATA

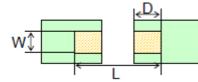
Item	General Specification					
Series No.	CLG12	CLG0A	CLG10	CLG06	CLG05	CLG03
Size code	2512 (6432)	2010 (5025)	1210 (3225)	1206 (3216)	0805 (2012)	0603 (1608)
Resistance			±5%,	±1%		
Tolerance						
Resistance	0.010Ω ~	0.050Ω ~	0.050Ω ~	0.010Ω ~	0.010Ω ~	0.050Ω ~
Range	0.910Ω, E24	0.910Ω, E24	0.910Ω, E24	0.910Ω, E24	0.910Ω, E24	0.910Ω, E24
TCR (ppm/°C)						
	10 - 20mΩ: ±1000			10 - 20mΩ: ±1000	10 - 20mΩ: ±1000	
	22 - 39mΩ: ±600			22 - 39mΩ: ±600	22 - 39mΩ: ±600	
	40 - 47mΩ: ±200			40 - 47mΩ: ±200	40 - 47mΩ: ±400	
	50 - 91mΩ: ±100	50 - 91mΩ: ±100	50 - 91mΩ: ±100	50 - 91mΩ: ±100	50 - 91mΩ: ±200	50 - 91mΩ: ±400
	100 - 910mΩ: ±100	100 - 910mΩ: ±100	100 - 910mΩ: ±100	100 - 910mΩ: ±100	100 - 910mΩ: ±100	100 - 910mΩ: ±200
Max. dissipation	2.14	1)//	2/4 \\\	2/4 \\/	1/2 \\/	4/4 \\\
at T _{amb} =70°C	2 W	1W	3/4 W	3/4 W	1/2 W	1/4 W
Operation	-55 ~ +155'C					
temperature			-55 ~ -	F 100 C		

MECHANICAL DATA



Symbol	CLG12	CLG0A	CLG10	CLG06	CLG05	CLG03
L	6.30 ± 0.20	5.00 ± 0.20	3.10 ± 0.10	3.10 ± 0.10	2.00 ± 0.10	1.60 ± 0.10
W	$\textbf{3.10}\pm\textbf{0.20}$	2.50 ± 0.20	2.60 ± 0.10	1.60 ± 0.10	1.25 ± 0.10	$\textbf{0.80} \pm \textbf{0.10}$
Т	0.65 ± 0.15	0.60 ± 0.10	0.55 ± 0.10	0.55 ± 0.10	0.50 ± 0.10	0.45 ± 0.10
Tt	0.60 ± 0.25	0.60 ± 0.25	0.50 ± 0.25	0.50 ± 0.25	0.40 ± 0.20	0.30 ± 0.20
Tb	0.90 ± 0.25	0.60 ± 0.25	0.90 ± 0.25	0.50 ± 0.25	0.40 ± 0.20	0.30 ± 0.20

RECOMMENDED SOLDERING PAD



Symbol	CLG12	CLG0A	CLG10	CLG06	CLG05	CLG03
WL	3.70mm	3.00mm	3.00mm	1.80mm	1.30mm	0.90mm
D	1.60mm	1.50mm	1.30mm	1.30mm	1.15mm	1.00mm
L	7.60mm	6.80mm	4.70mm	4.70mm	3.50mm	3.00mm



MARKING

• 4-digits marking for 2512, 2010, 1210, 1206, 0805 size

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

- 3-digits marking for 0603 size
- Each resistor is marked with a three -digit code on the protective coating to designate the nominal resistance value.

Resistance Marking (E-24 Series)

R150	4 digit marking for ±1%,±5% 0005, 1200, 1210,2010, 2512
R50	Examples. R150 = 150 m Ω , R020 = 20 m Ω 3 digit marking for ±1%,±5% 0603 Examples. R12 = 120 m Ω , R50 = 500 m Ω
47M	3 digit marking for ±1%,±5% 0603 (47mΩ~91mΩ) Examples. 20M = 20 mΩ

FUNCTIONAL DESCRIPTION

Product characterization

Standard values of nominal resistance are taken from the E24 series for resistors with a tolerance of $\pm 5\%$ & $\pm 1\%$. The values of the E24 series are in accordance with "IEC publication 60063".

Derating curve

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

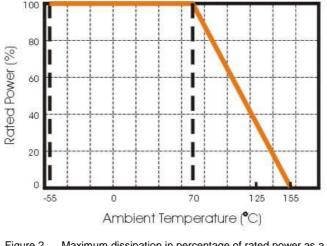


Figure 2 Maximum dissipation in percentage of rated power as a function of the ambient temperature

MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.

SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

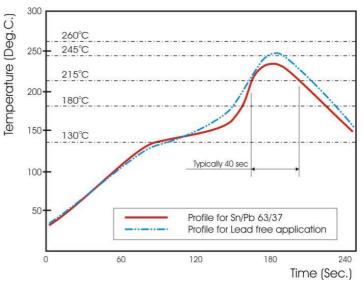


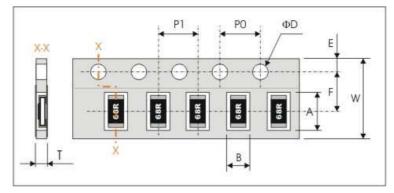
Fig 3. Infrared soldering profile

TEST	PROCEDURE	REQUIREMENT
Temperature Coefficient of Resistance(T.C.R) Clause 4.8	Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C) } t_1 : 25 \text{°C}$	Refer to "QUICK REFERENCE DATA"
	R_1 : Resistance at reference temperature 25°C R_2 : Resistance at test temperature 155°C	
Short time overload (S.T.O.L) Clause 4.13	Permanent resistance change after a 5second application of a 5 times rated power.	J: ΔR/R max. ±(2%+0.5mΩ) F: ΔR/R max. ±(1%+0.5mΩ)
Solderability Clause 4.17	Un-mounted chips completely immersed for 3±0.5 second in a SAC solder bath at 245 $^\circ\!C$ ±2 $^\circ\!C$	good tinning (>95% covered) no visible damage
Resistance to soldering heat(R.S.H) Clause 4.18	Un-mounted chips completely immersed for 10±1 second in a SAC solder bath at $260^\circ\!{\rm C}$ ±5 $^\circ\!{\rm C}$	no visible damage J: ΔR/R max. ±(1%+0.5mΩ) F: ΔR/R max. ±(0.5%+0.5mΩ)
Temperature cycling Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +155°C±3°C, 2~3 minutes at 20°C+5°C-1°C, total 5 continuous cycles	no visible damage J: Δ R/R max. ±(1%+0.5mΩ) F: Δ R/R max. ±(0.5%+0.5mΩ)
Load life (endurance) Clause 4.25	1000 +48/-0 hours, loaded with RCWV or Vmax in chamber controller $70\pm2^{\circ}$ C, 1.5 hours on and 0.5 hours off	J: ΔR/R max. ±(3%+0.5mΩ) F: ΔR/R max. ±(1%+0.5mΩ)
Load life in Humidity Clause 4.24	1000 +48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at 40°C±2°C and 90~95% relative humidity, 1.5hours on and 0.5 hours off	J: ΔR/R max. ±(3%+0.5mΩ) F: ΔR/R max. ±(1%+0.5mΩ)
Bending strength Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4); bending : 3mm for 0603/0805, 2mm for 1206 and above sizes, once for 10 seconds	no visible damage J: Δ R/R max. ±(1%+0.5mΩ) F: Δ R/R max. ±(0.5%+0.5mΩ)
Adhesion Clause 4.32	Pressurizing force: 5N, Test time: 10±1sec.	No remarkable damage or removal of the terminations
Insulation Resistance Clause 4.6	Test voltage: 100+/-15V	I.R≧1GΩ

TEST AND REQUIREMENTS(JIS C 5201-1 : 1998)

PACKAGING

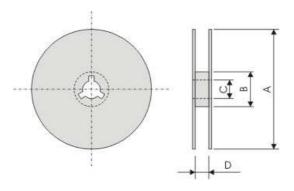
Paper Tape specifications (unit :mm)



Series No.	А	В	W	F	E
CLG12	6.70±0.20	3.50±0.20	12.00±0.30		
CLG0A	5.50±0.20	2.80±0.20	12.00±0.30		
CLG10	3.60±0.20	3.00±0.20		3.50±0.20	1.75±0.10
CLG06	3.60±0.20	2.00±0.20	8.00±0.30		
CLG05	2.40±0.20	1.65±0.20			
CLG03	1.90±0.20	1.10±0.20			

Series No.	P1	P0	ΦD	Т
CLG12				Max. 1.2
CLG0A				Max. 1.2
CLG10	4.00±0.10	4.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	Max. 1.0
CLG06	4.00±0.10			Max. 1.0
CLG05				
CLG03				Max. 0.8

Reel dimensions



Symbol	А	В	С	D
7" reel	Φ178.0±2.0	Φ60.0±1.0		10.0 ± 1.5 (9mm tone)
10" reel	Φ254.0±2.0	Φ100.0±1.0	13.0±0.5	10.0±1.5(8mm tape) 13.8±1.5 (12mm tape)
13: reel	Ф330.0±2.0	Φ100.0±1.0		13.0±1.3 (1211111 tape)